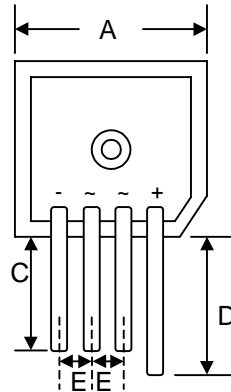


Features

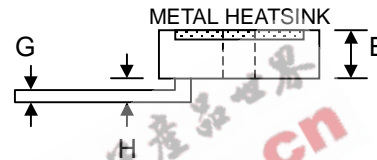
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space

Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



| KBPC-S | | |
|----------------------|----------------|-------|
| Dim | Min | Max |
| A | 28.40 | 28.70 |
| B | 10.97 | 11.23 |
| C | 13.90 | — |
| D | 19.10 | — |
| E | 5.10 | — |
| G | 1.20 Ø Typical | |
| H | 3.05 | 3.60 |
| All Dimensions in mm | | |



Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| Characteristics | Symbol | -00GS | -01GS | -02GS | -04GS | -06GS | -08GS | -10GS | Unit |
|--|-----------------|-------|-------|-------|-------------|-------|-------|-------|------------------|
| Peak Repetitive Reverse Voltage | V_{RRM} | | | | | | | | V |
| Working Peak Reverse Voltage | V_{RWM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | |
| DC Blocking Voltage | V_R | | | | | | | | |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Average Rectified Output Current @ $T_C = 55^\circ\text{C}$ | I_O | | | | 40 50 | | | | A |
| Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method) | I_{FSM} | | | | 400 400 | | | | A |
| Forward Voltage Drop (per element) | V_{FM} | | | | 1.1 | | | | V |
| Peak Reverse Current at Rated DC Blocking Voltage (per element) | I_R | | | | 5.0 500 | | | | μA |
| Typical Thermal Resistance (per element) (Note 1) | $R_{\theta JC}$ | | | | 1.5 | | | | K/W |
| RMS Isolation Voltage from Case to Lead | V_{ISO} | | | | 2500 | | | | V |
| Operating and Storage Temperature Range | T_j, T_{STG} | | | | -65 to +150 | | | | $^\circ\text{C}$ |

Note: 1. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.

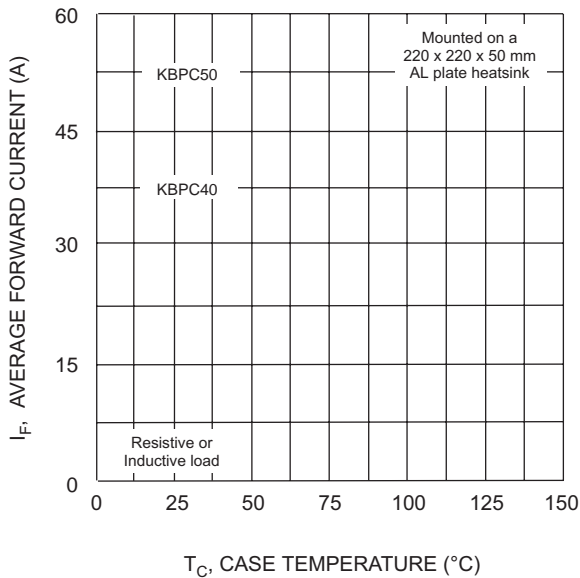


Fig. 1 Forward Current Derating Curve

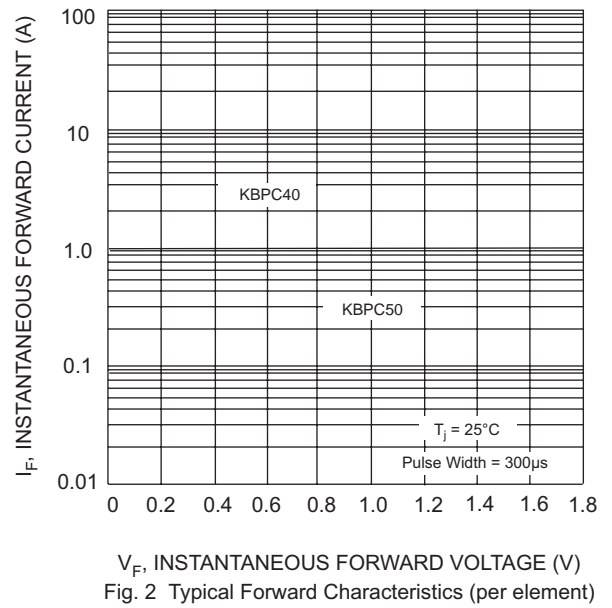


Fig. 2 Typical Forward Characteristics (per element)

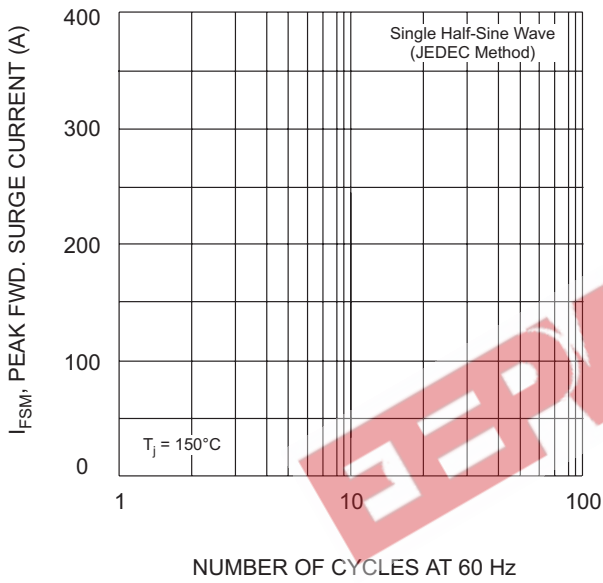


Fig. 3 Max Non-Repetitive Surge Current

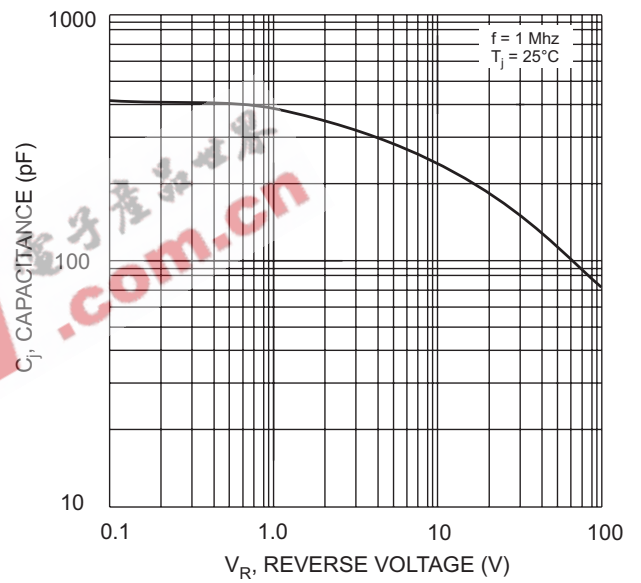


Fig. 4 Typical Junction Capacitance (per element)

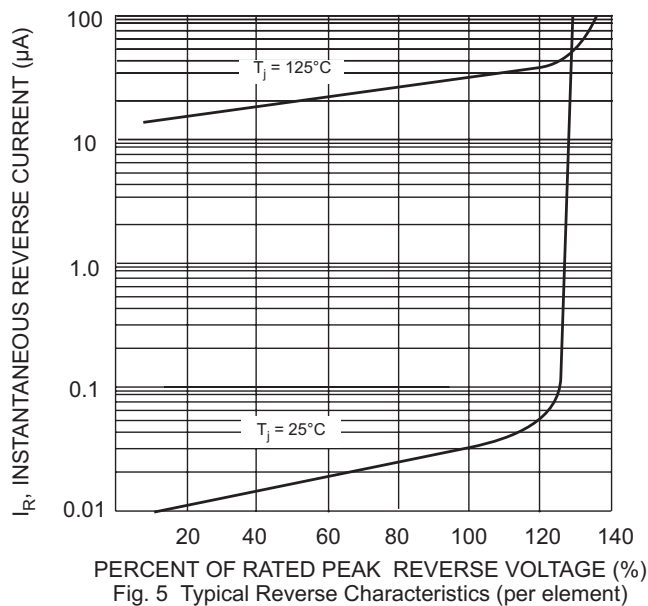


Fig. 5 Typical Reverse Characteristics (per element)

ORDERING INFORMATION

| Product No. | Package Type | Shipping Quantity |
|-------------|--------------|-------------------|
| KBPCxx00GS | SIL Bridge | 72 Units/Box |
| KBPCxx01GS | SIL Bridge | 72 Units/Box |
| KBPCxx02GS | SIL Bridge | 72 Units/Box |
| KBPCxx04GS | SIL Bridge | 72 Units/Box |
| KBPCxx06GS | SIL Bridge | 72 Units/Box |
| KBPCxx08GS | SIL Bridge | 72 Units/Box |
| KBPCxx10GS | SIL Bridge | 72 Units/Box |

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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